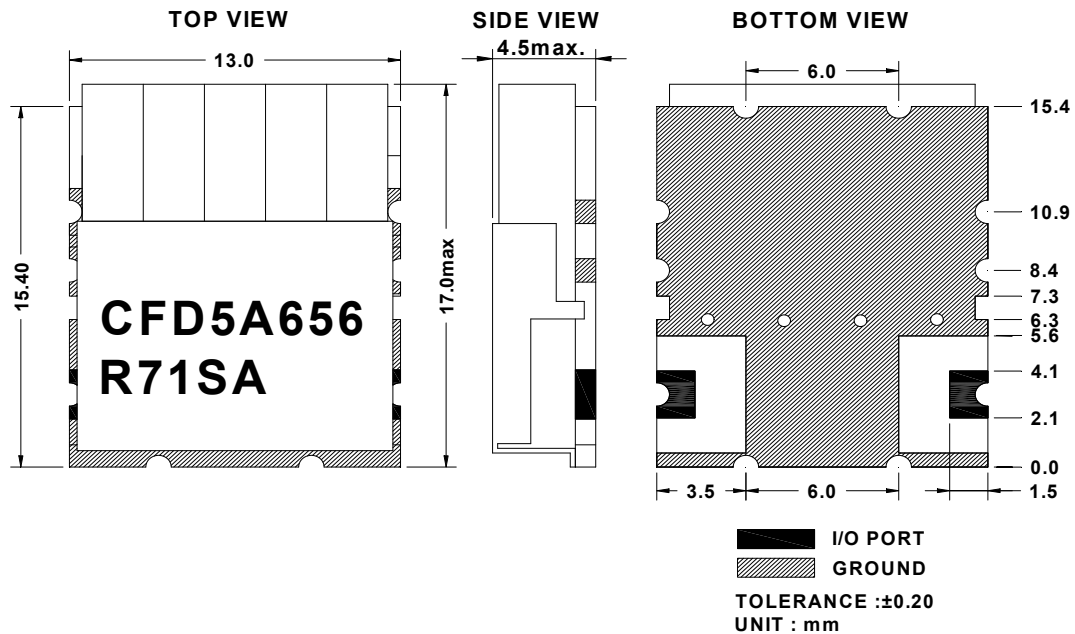


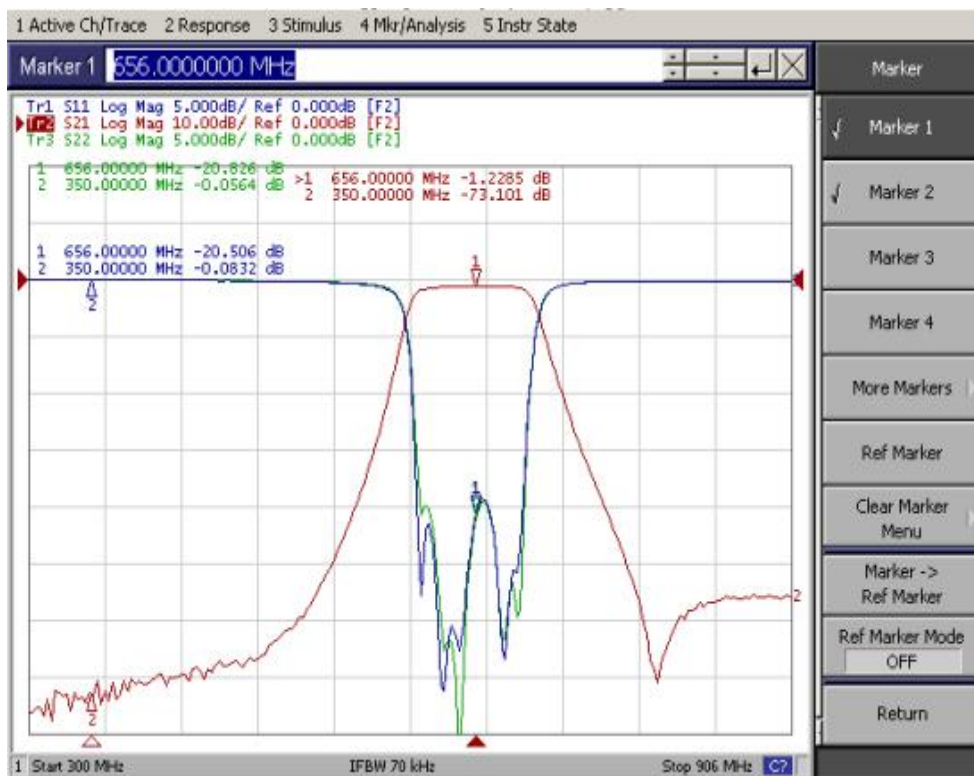
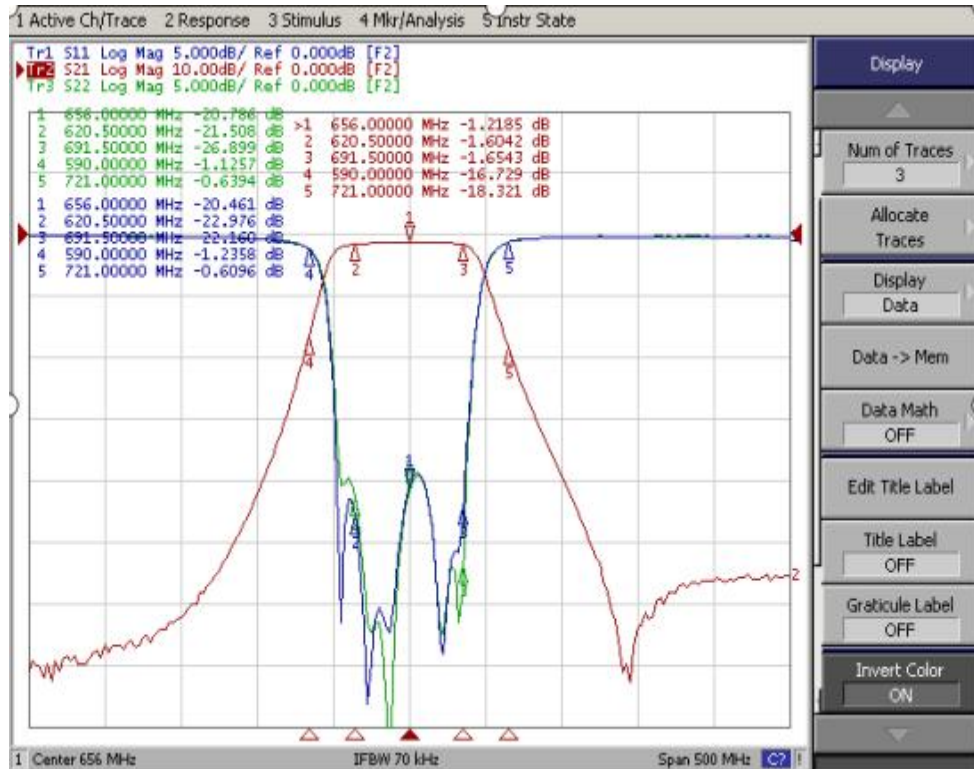
Electrical Specification

| ITEMS | SPEC | UNIT |
|--|-------------------------------|--------|
| Center Frequency [fo] | 656.0 | MHz |
| Bandwidth [BW] | fo ±35.5 [620.5 ~ 691.5] | MHz |
| Insertion Loss in BW | 2.0 | dB max |
| Ripple in BW | 0.5 | dB max |
| Return Loss in BW | 15.0 | dB min |
| Attenuation <input checked="" type="checkbox"/> Absolute Value <input type="checkbox"/> Relative Value | 14.0 dB min @ fo ± [590.0 &] | MHz |
| | 12.0 dB min @ fo ± [721.0 &] | MHz |
| | 60.0 dB min @ fo ± [350.0 ~] | MHz |
| | dB min @ fo ± [&] | MHz |
| Group Delay Variation | 5 | ns max |
| Input Power | 2.0 | W max. |
| In/Out Impedance | 50 Ω | |
| Operation Temperature Range | -40°C to +85°C | |

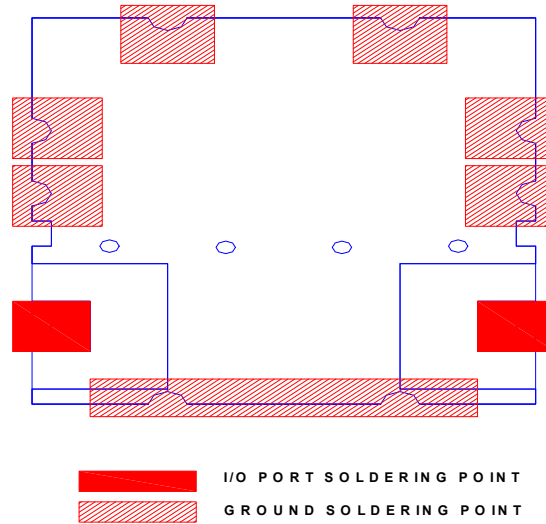
Mechanical Specification



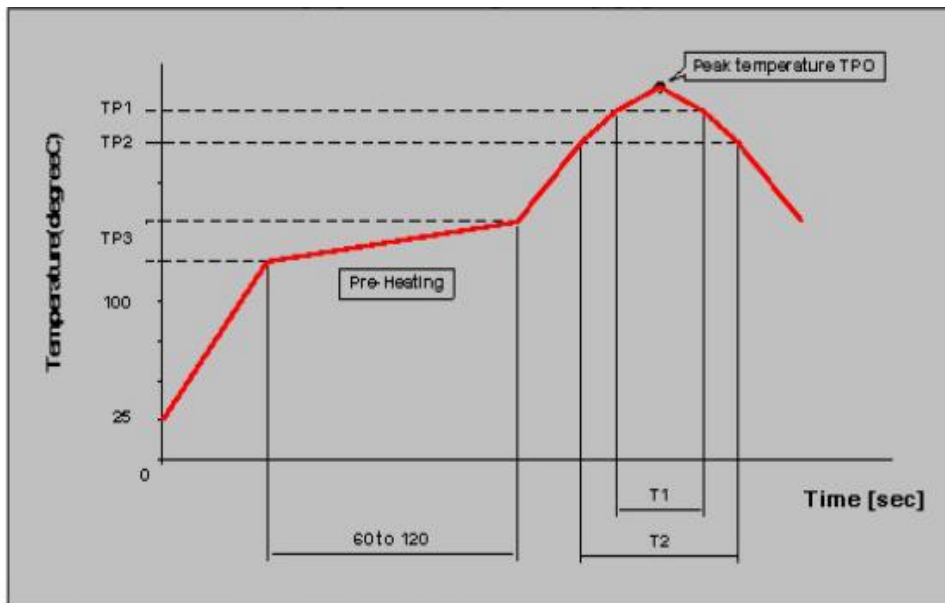
Plot Data



Recommanded PC Board Pattern



Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

| Reflow standard condition | TP0 (°C) | TP1 (°C) | T1 (s) | TP2 (°C) | T2 (s) | TP3 (°C) |
|--|----------|----------|----------|----------|--------|------------|
| Sn-3Ag-0.5 solder | 245±5 | 220 | 30 to 60 | — | — | 150 to 180 |
| Test condition of reflow heat resistance | 260±5/0 | 240 | 20 | 220 | 70 | 150 to 180 |